



Docket No.: M4065.0226/P226
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Tongbi Jiang

Application No.: 09/484,437

Confirmation No.: 9698

Filed: January 18, 2000

Art Unit: 2827

For: DIE ATTACH CURING METHOD FOR
BGA PRODUCT

Examiner: J. M. Mitchell

*Entered
w/ RCE
3.28.05*

AMENDMENT AFTER FINAL ACTION (37 C.F.R. SECTION 1.116)

*ML
4-2-05*

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated December 14, 2004 (Paper No. 1212), finally rejecting claims 1-9, 11, 12, 14-20, and 33-40, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.

DO NOT ENTER, OK, 3/19/2005